MA2YD260G

Silicon epitaxial planar type

For high speed switching

Features

- Forward current (Average) $I_{F(AV)} = 800$ mA rectification is possible
- Reverse voltage $V_R = 60$ V is guaranteed
- \bullet Small reverse current I_{R}
- Mini type 2-pin package

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	60	V
Maximum peak reverse voltage	V _{RM}	60	V
Forward current (Average) *1	I _{F(AV)}	800	mA
Non-repetitive peak forward surge current *2	I _{FSM}	3	А
Junction temperature	Tj	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

2: Cathode

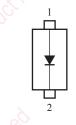
Package
Code

Mini2-F2

Pin Name

1: Anode

- Marking Symbol: 2Y
- Internal Connection



Note) *1: Mounted on a alumina PC board

*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

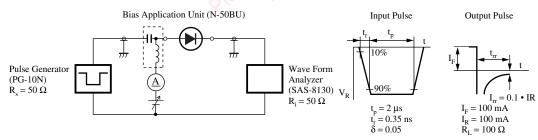
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	I _F = 800 mA	20	0.51	0.58	V
Reverse current	IR	V _R = 45 V	, de	0-	100	μΑ
Terminal capacitance	C _t	$V_R = 0 V, f = 1 MHz$	$\sim 2^{\circ}$	125		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		8		ns
		$I_{rr} = 0.1 \bullet I_R$, $R_L = 100 \Omega$				

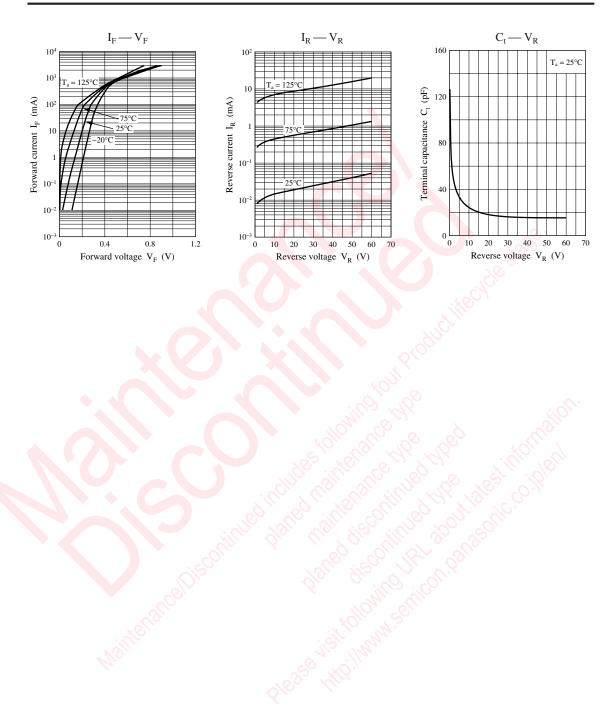
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

- 3. Rated input/output frequency: 250 MHz
- 4. *: t_{rr} measuring instrument

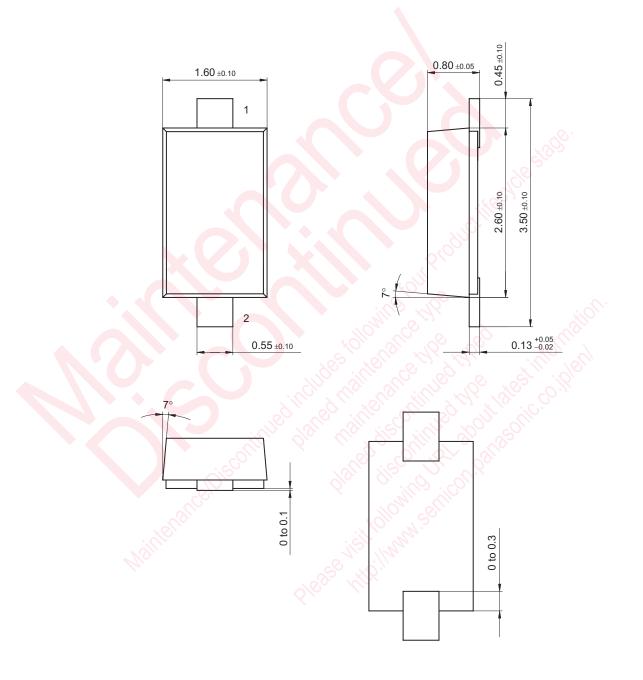


MA2YD260G



Mini2-F2

Unit: mm



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